



## GaN HEMT Power Transistor 30W CW, 30 MHz - 3.5 GHz

Preliminary, 23 Aug 11

### Features

- GaN depletion mode HEMT microwave transistor
- Common source configuration
- No internal matching
- Broadband Class AB operation
- Thermally enhanced Cu/Mo/Cu package
- RoHS Compliant
- +50V Typical Operation
- MTTF of 114 years (Channel Temperature < 200°C)

### Applications

General purpose for pulsed or CW applications

- Commercial Wireless Infrastructure  
- WCDMA, LTE, WIMAX
- Civilian and Military Radar
- Military and Commercial Communications
- Public Radio
- Industrial, Scientific and Medical
- SATCOM
- Instrumentation
- Avionics



### Product Description

The MAGX-000035-030000 is a gold metalized unmatched Gallium Nitride (GaN) on Silicon Carbide RF power transistor suitable for a variety of RF power amplifier applications. Using state of the art wafer fabrication processes, these high performance transistors provide high gain, efficiency, bandwidth, ruggedness over multiple octave bandwidths for today's demanding application needs. The MAGX-000035-030000 is constructed using a thermally enhanced Cu/Mo/Cu flanged ceramic package which provides excellent thermal performance. High breakdown voltages allow for reliable and stable operation in extreme mismatched load conditions unparalleled with older semiconductor technologies.

### Typical CW RF Performance

Freq. (MHz)	Pout (W Ave)	Gain (dB)	Eff (%)
30	58	40	80
100	44	32	65
500	43	27	66
1500	42	20	59
3000	35	13	55
3500	30	12	53

### Ordering Information

MAGX-000035-030000      30W GaN Power Transistor  
MAGX-000035-SB1PPR      1.5 GHz Evaluation Board

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<b>Absolute Maximum Ratings (1, 2, 3)</b>	<b>Limit</b>
Supply Voltage (Vdd)	+65V
Supply Voltage (Vgg)	-8 to 0V
Supply Current (Id1)	1200 mA
Input Power (Pin)	+30 dBm
Junction/Channel Temp	200 °C
MTTF (T <sub>J</sub> <200°C)	114 years
Continuous Power Dissipation (Pdiss) at 85 °C	27 W
Pulsed Power Dissipation (Pavg) at 85 °C	65 W
Thermal Resistance, (Tchannel = 200 °C), CW	4.2 °C/W
Thermal Resistance, (Tchannel = 200 °C), Pulsed 500uS, 10% Duty cycle	1.8 °C/W
Operating Temp	-40 to +95C
Storage Temp	-65 to +150C
ESD Min. - Machine Model (MM)	50 V
ESD Min. - Human Body Model (HBM)	>250 V

- (1) Operation of this device above any one of these parameters may cause permanent damage.
- (2) Channel temperature directly affects a device's MTTF. Channel temperature should be kept as low as possible to maximize lifetime.
- (3) For saturated performance it recommended that the sum of  $(3 \cdot V_{dd} + \text{abs}(V_{gg})) < 175$

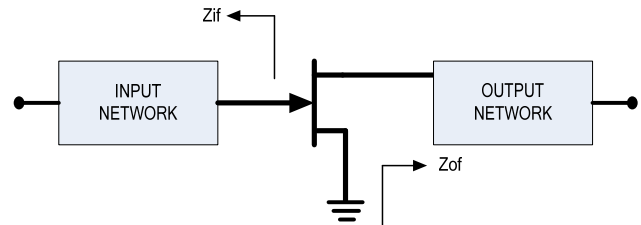
<b>Parameter</b>	<b>Test Conditions</b>	<b>Symbol</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Units</b>
<b>DC CHARACTERISTICS</b>						
Drain-Source Leakage Current	V <sub>GS</sub> = -8V, V <sub>DS</sub> = 175V	I <sub>DS</sub>	-	-	2.5	mA
Gate Threshold Voltage	V <sub>DS</sub> = 5V, I <sub>D</sub> = 6mA	V <sub>GS(th)</sub>	-5	-3	-2	V
Forward Transconductance	V <sub>DS</sub> = 5V, I <sub>D</sub> = 1.5mA	G <sub>M</sub>	1.0	-	-	S
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	V <sub>DS</sub> = 0V, V <sub>GS</sub> = -8V, F = 1MHz	C <sub>ISS</sub>	-	13.2	-	pF
Output Capacitance	V <sub>DS</sub> = 50V, V <sub>GS</sub> = -8V, F = 1MHz	C <sub>OSS</sub>	-	5.6	-	pF
Reverse Transfer Capacitance	V <sub>DS</sub> = 50V, V <sub>GS</sub> = -8V, F = 1MHz	C <sub>RSS</sub>	-	0.5	-	pF

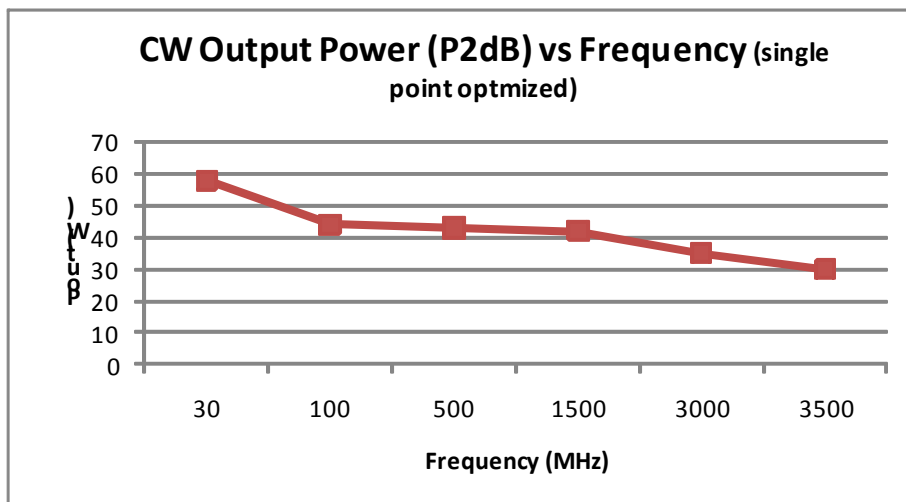
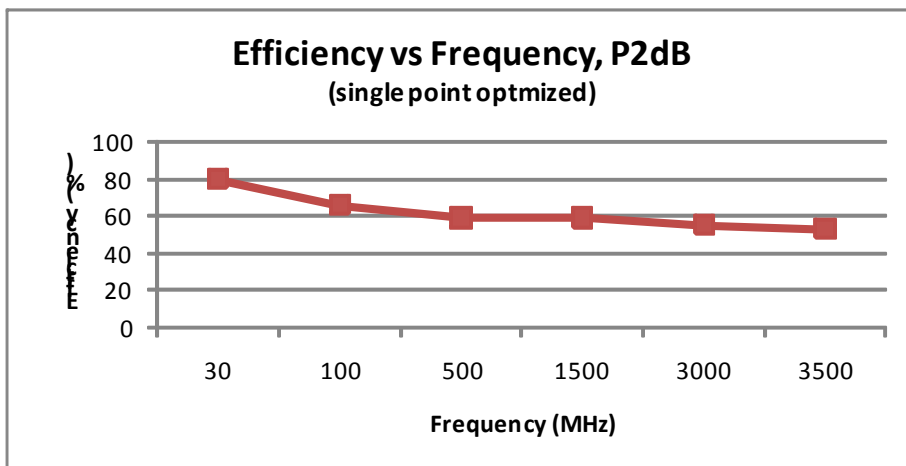
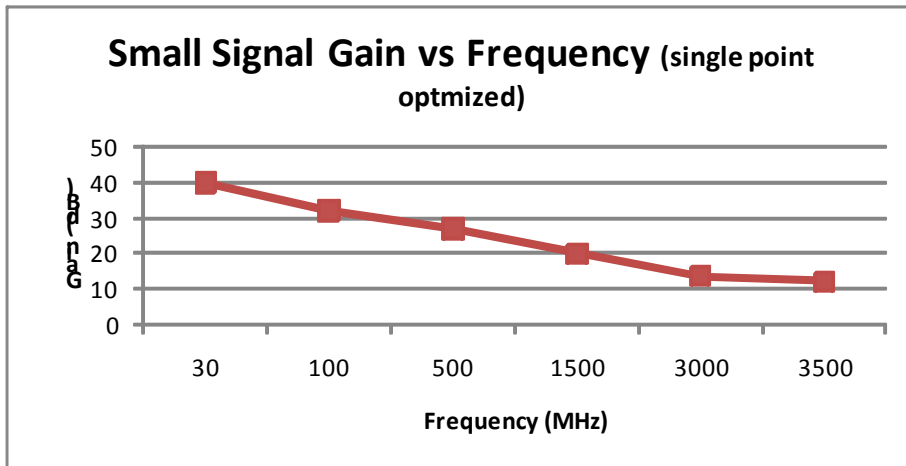
**Electrical Specifications:  $T_c = 25 \pm 5^\circ\text{C}$  (Room Ambient )**

Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
<b>RF FUNCTIONAL TESTS</b> <i>V<sub>dd</sub>=50V, I<sub>dq</sub>= 100 mA, single frequency optimized data</i>						
CW Output Power (P <sub>2dB</sub> ) 1 .5GHz	Pin = 1W Ave	P <sub>OUT</sub>	30	42	-	W Ave
CW Output Power (P <sub>2dB</sub> ) 3 GHz	Pin = 1W Ave	P <sub>OUT</sub>	30	31	-	W Ave
Small Signal Gain @ 1.5 GHz	P <sub>out</sub> = 5W Ave	G <sub>P</sub>	18	20		dB
Small Signal Gain @ 3 GHz	P <sub>out</sub> = 5W Ave	G <sub>P</sub>	13	13.6		dB
Drain Efficiency @ 3 GHz	Pin = 1W Ave	$\eta_D$	50	60		%
Load Mismatch Stability	Pin = 1W Ave	VSWR-S	5:1	-	-	-
Load Mismatch Tolerance	Pin = 1W Ave	VSWR-T	10:1	-	-	-

**Test Fixture Impedance**

F (MHz)	Z <sub>if-opt</sub> (Ω)	Z <sub>of-opt</sub> (Ω)
30	71 + j 255	24.9 - j 6.8
100	7.7 + j 66.6	22.14 - j 4.33
500	3.19 + j 13.8	21.8 + j 9.94
1500	1.4 + j 0.16	9.31 + j 9.34
3000	3.1 - j 9.96	3.32 + j 1.2
3500	TBD	TBD





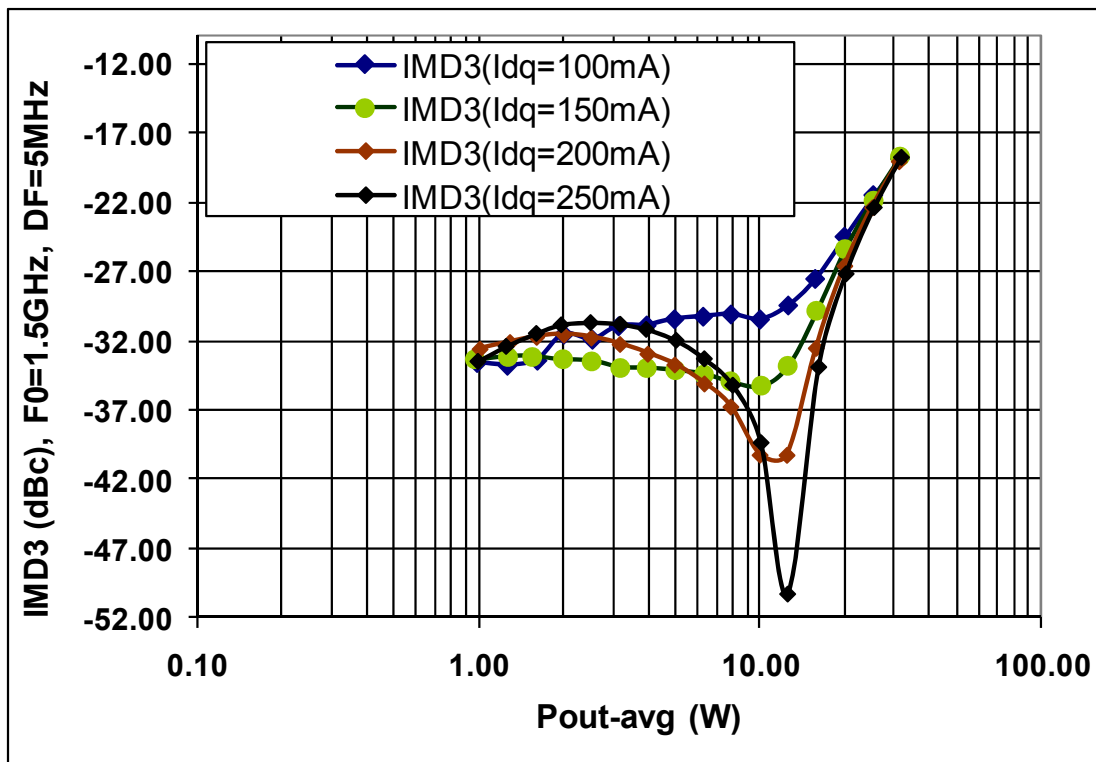
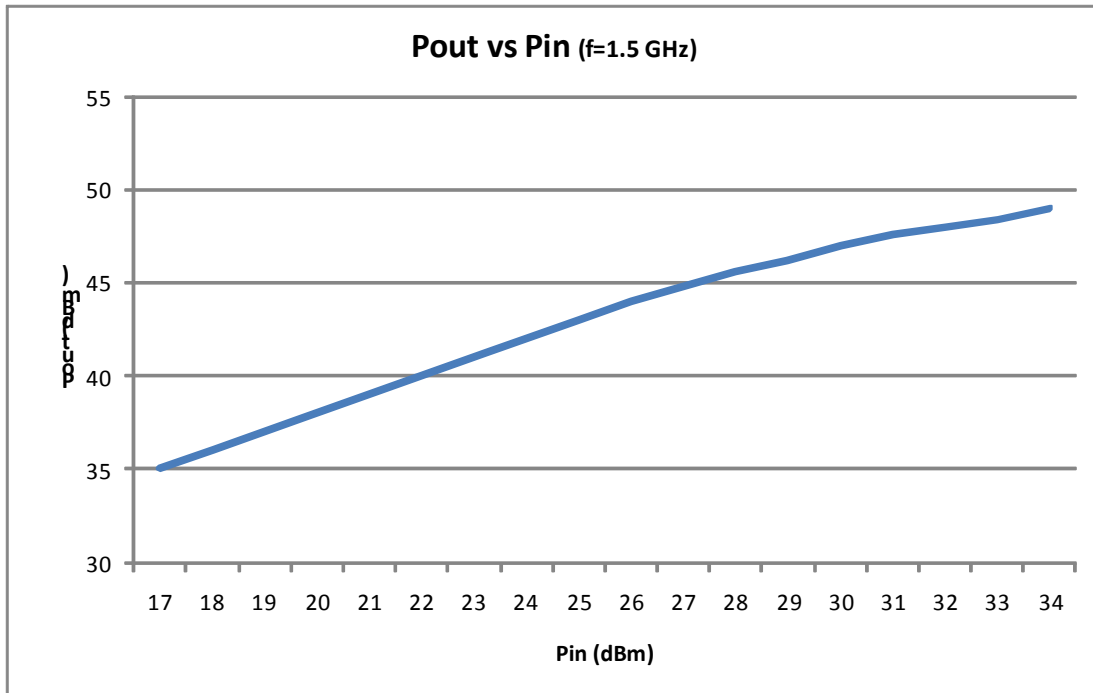
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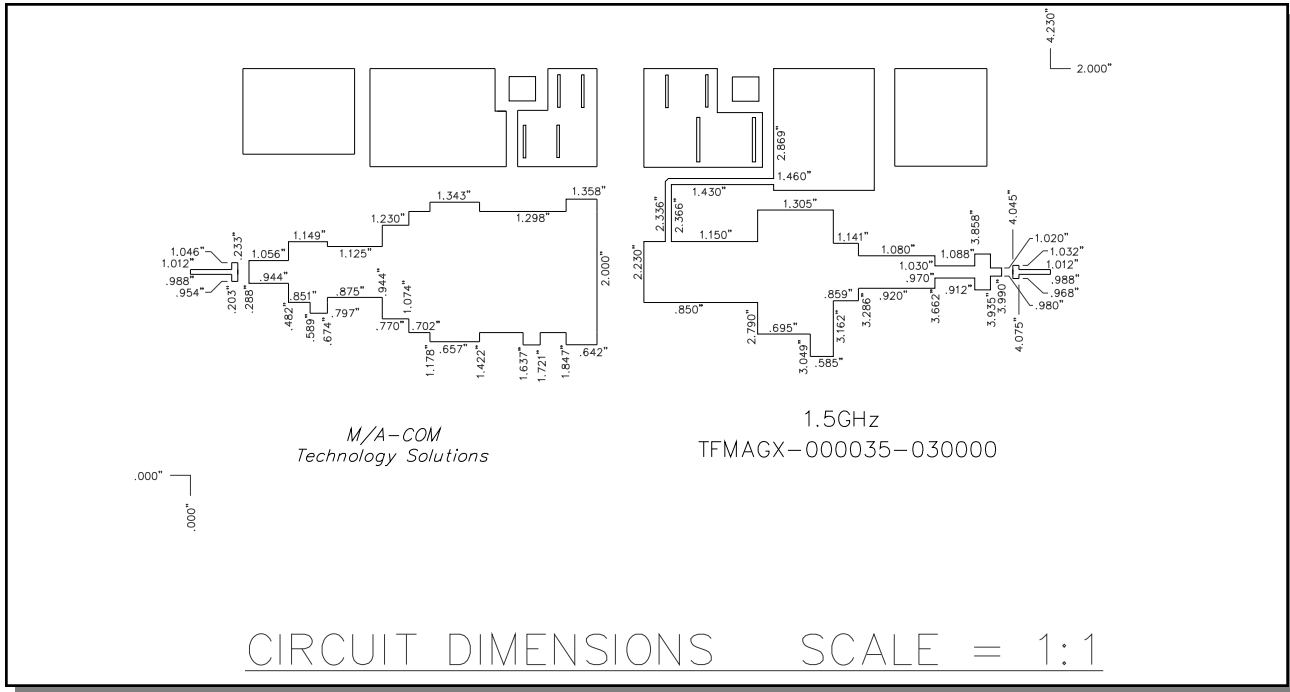
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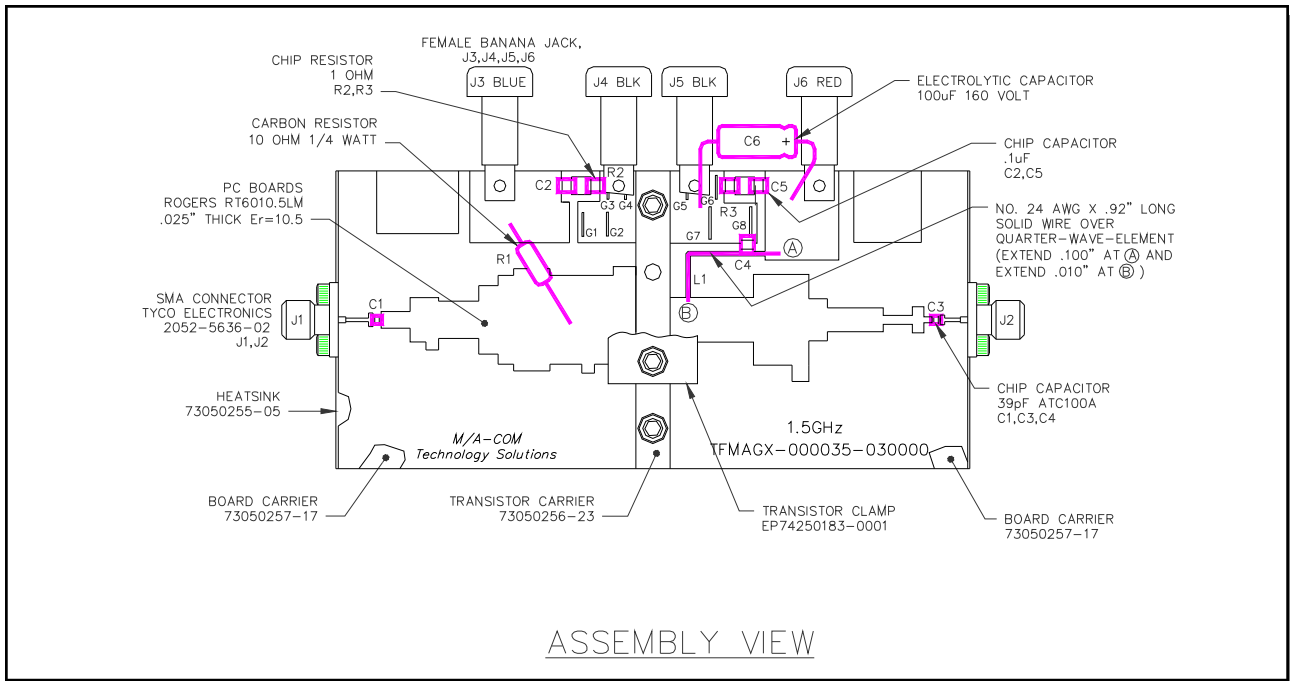
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1.5 GHz Test Fixture Circuit Dimensions



1.5 GHz Test Fixture Assembly



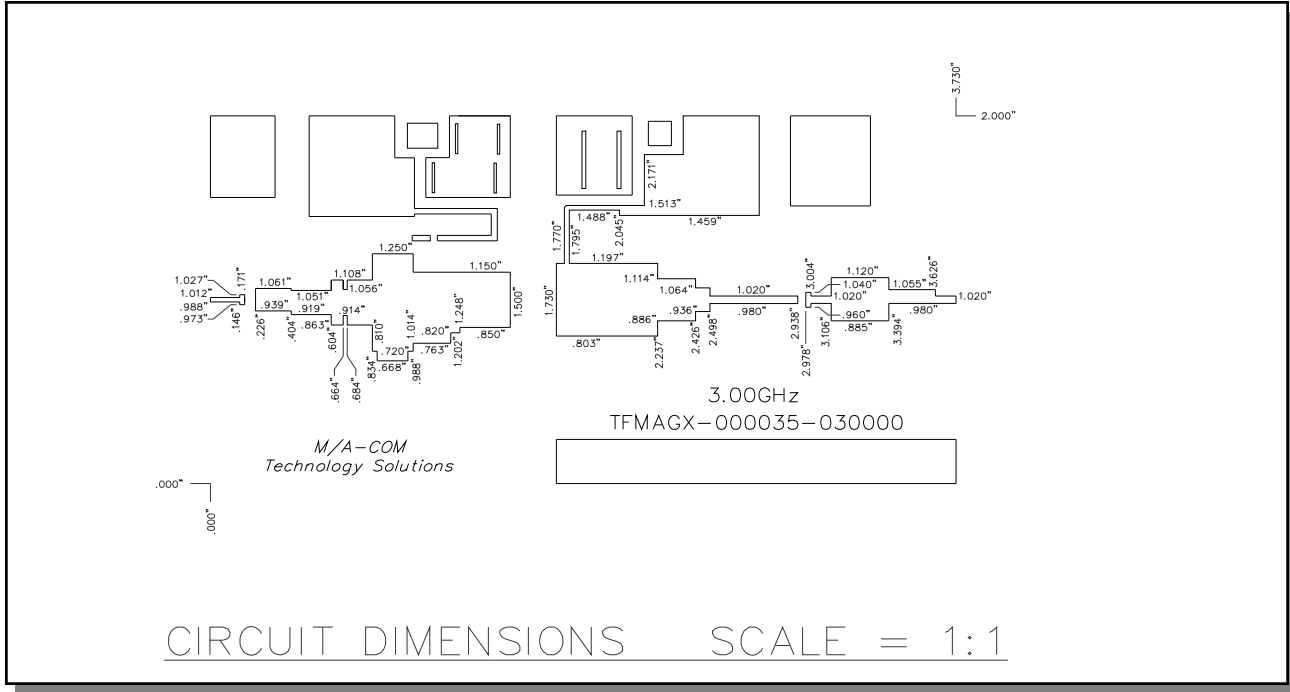
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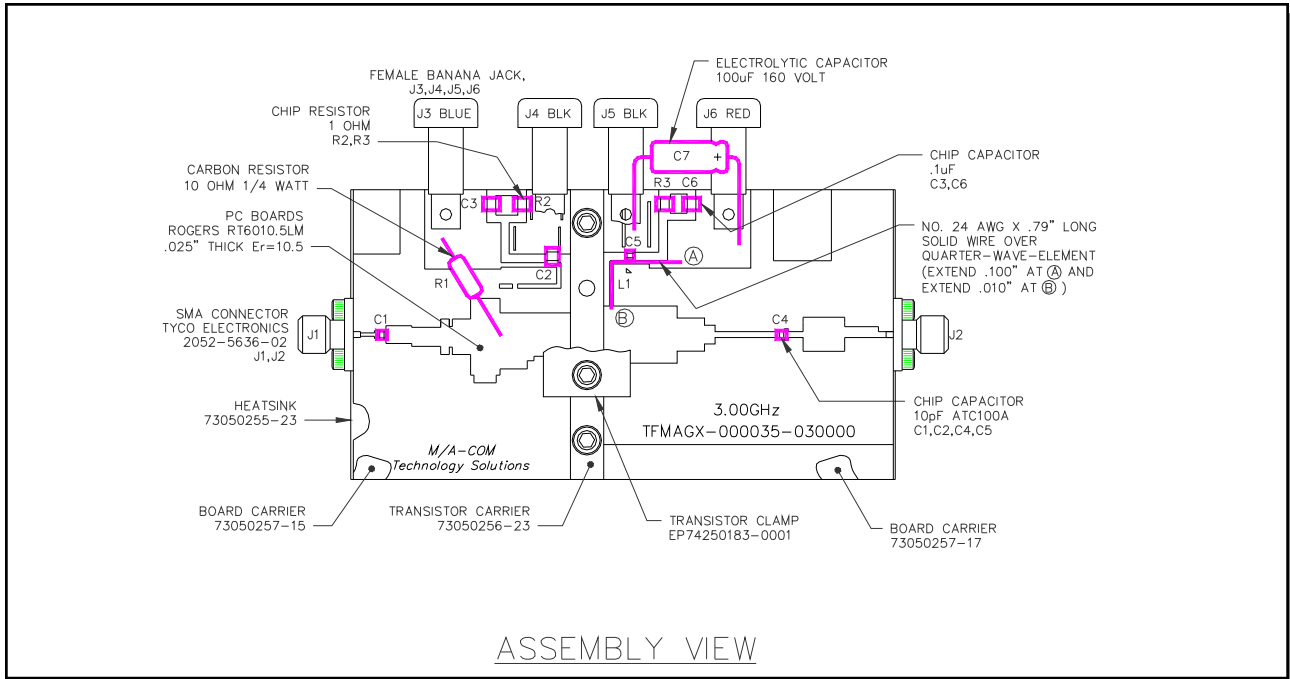
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3 GHz Test Fixture Circuit Dimensions



3 GHz Test Fixture Assembly



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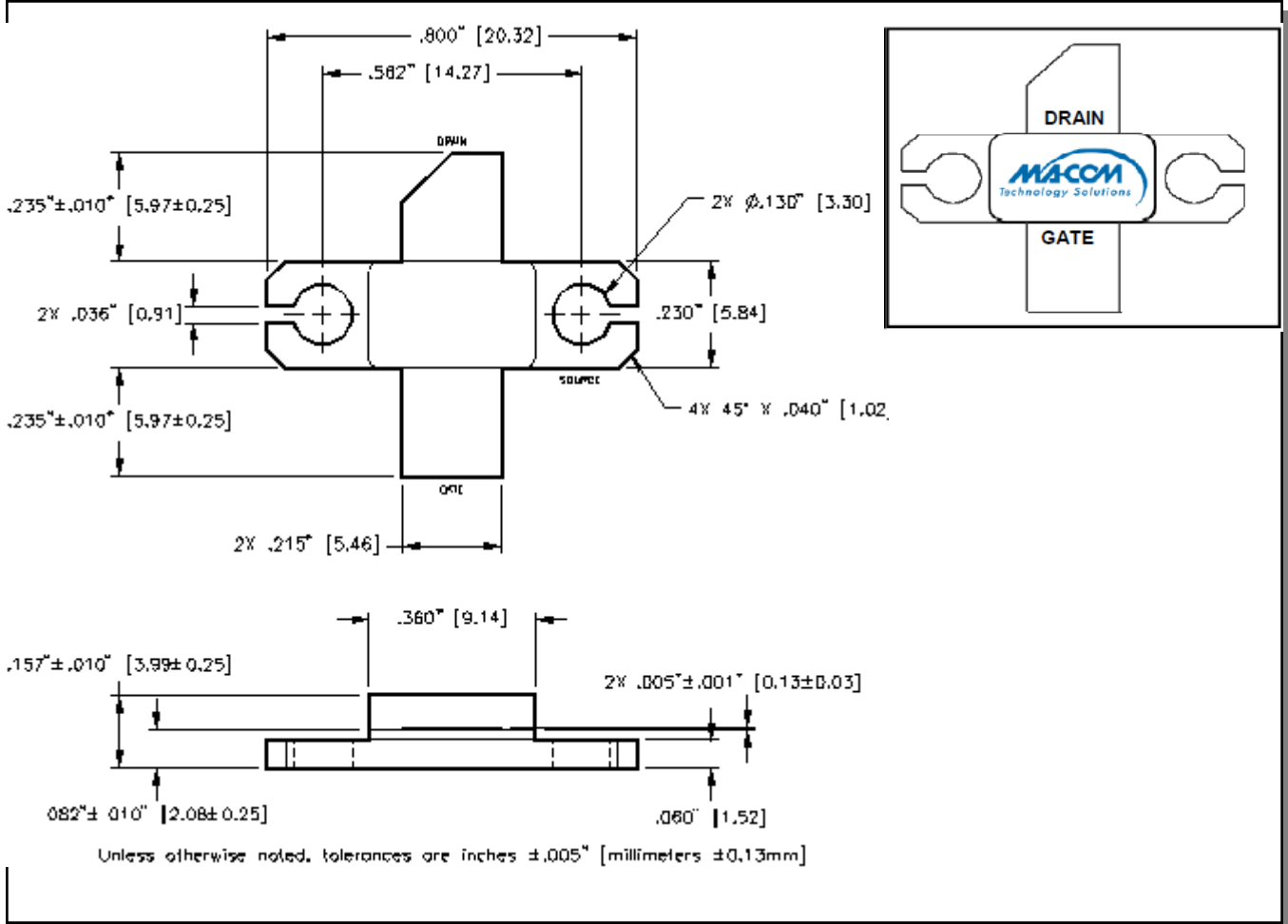
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**Outline Drawings**



**CORRECT DEVICE SEQUENCING**

**TURNING THE DEVICE ON**

1. Set  $V_{GS}$  to the pinch-off ( $V_P$ ), typically -5V
2. Turn on  $V_{DS}$  to nominal voltage (50V)
3. Increase  $V_{GS}$  until the  $I_{DS}$  current is reached
4. Apply RF power to desired level

**TURNING THE DEVICE OFF**

1. Turn the RF power off
2. Decrease  $V_{GS}$  down to  $V_P$
3. Decrease  $V_{DS}$  down to 0V
4. Turn off  $V_{GS}$